



# PMG85XP

20 V, 2 A P-channel Trench MOSFET

Rev. 1 — 28 June 2011

Product data sheet

## 1. Product profile

### 1.1 General description

P-channel enhancement mode Field-Effect Transistor (FET) in a very small SOT363 (SC-88) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

### 1.2 Features and benefits

- Low threshold voltage
- Very fast switching
- Trench MOSFET technology

### 1.3 Applications

- Relay driver
- High-speed line driver
- High-side loadswitch
- Switching circuits

### 1.4 Quick reference data

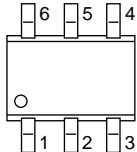
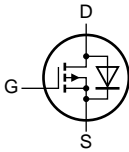
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$T_j = 25\text{ °C}$	-	-	-20	V
$V_{GS}$	gate-source voltage		-12	-	12	V
$I_D$	drain current	$V_{GS} = -4.5\text{ V}; T_j = 25\text{ °C}$	[1]	-	-2	A
<b>Static characteristics</b>						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = -4.5\text{ V}; I_D = -2\text{ A}; T_j = 25\text{ °C}$	-	90	115	m $\Omega$

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.

## 2. Pinning information

**Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	D	drain	 <p><b>SOT363 (TSSOP6)</b></p>	 <p>017aaa094</p>
2	D	drain		
3	G	gate		
4	S	source		
5	D	drain		
6	D	drain		

## 3. Ordering information

**Table 3. Ordering information**

Type number	Package		
	Name	Description	Version
PMG85XP	TSSOP6	plastic surface-mounted package; 6 leads	SOT363

## 4. Marking

**Table 4. Marking codes**

Type number	Marking code <sup>[1]</sup>
PMG85XP	YA%

[1] % = placeholder for manufacturing site code

## 5. Limiting values

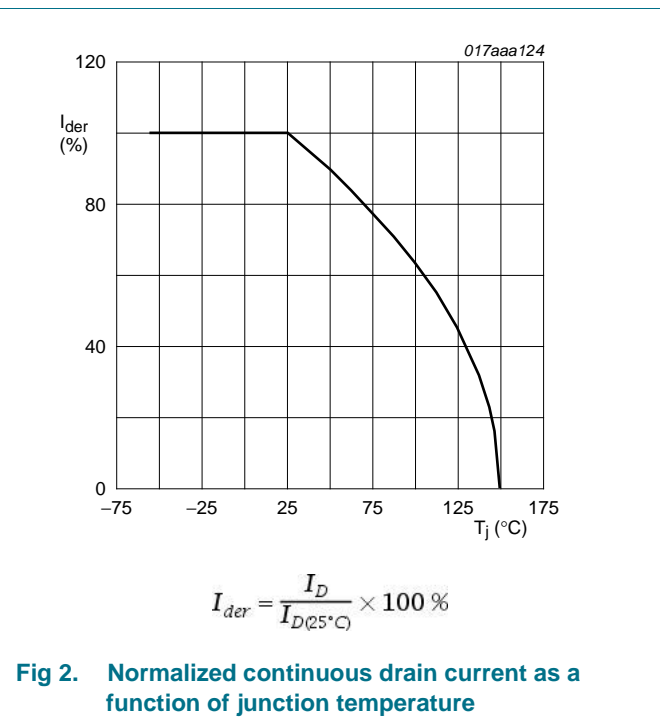
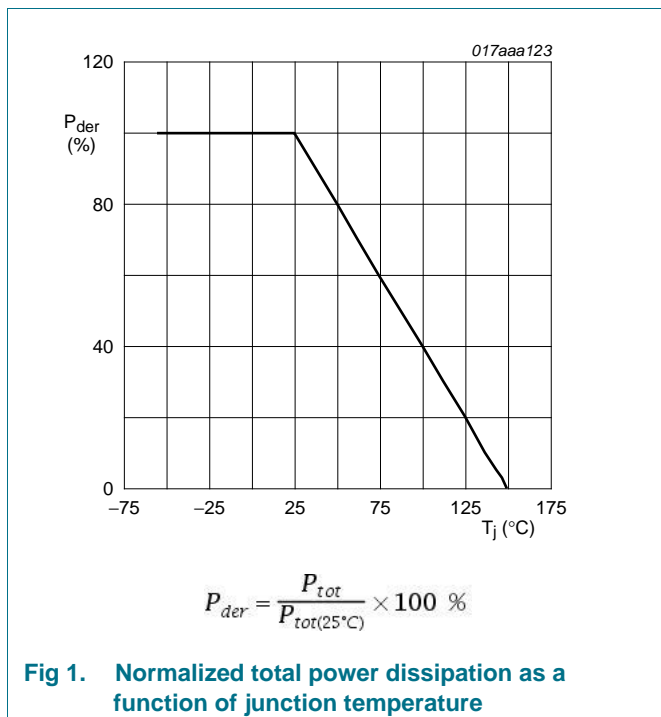
**Table 5. Limiting values**

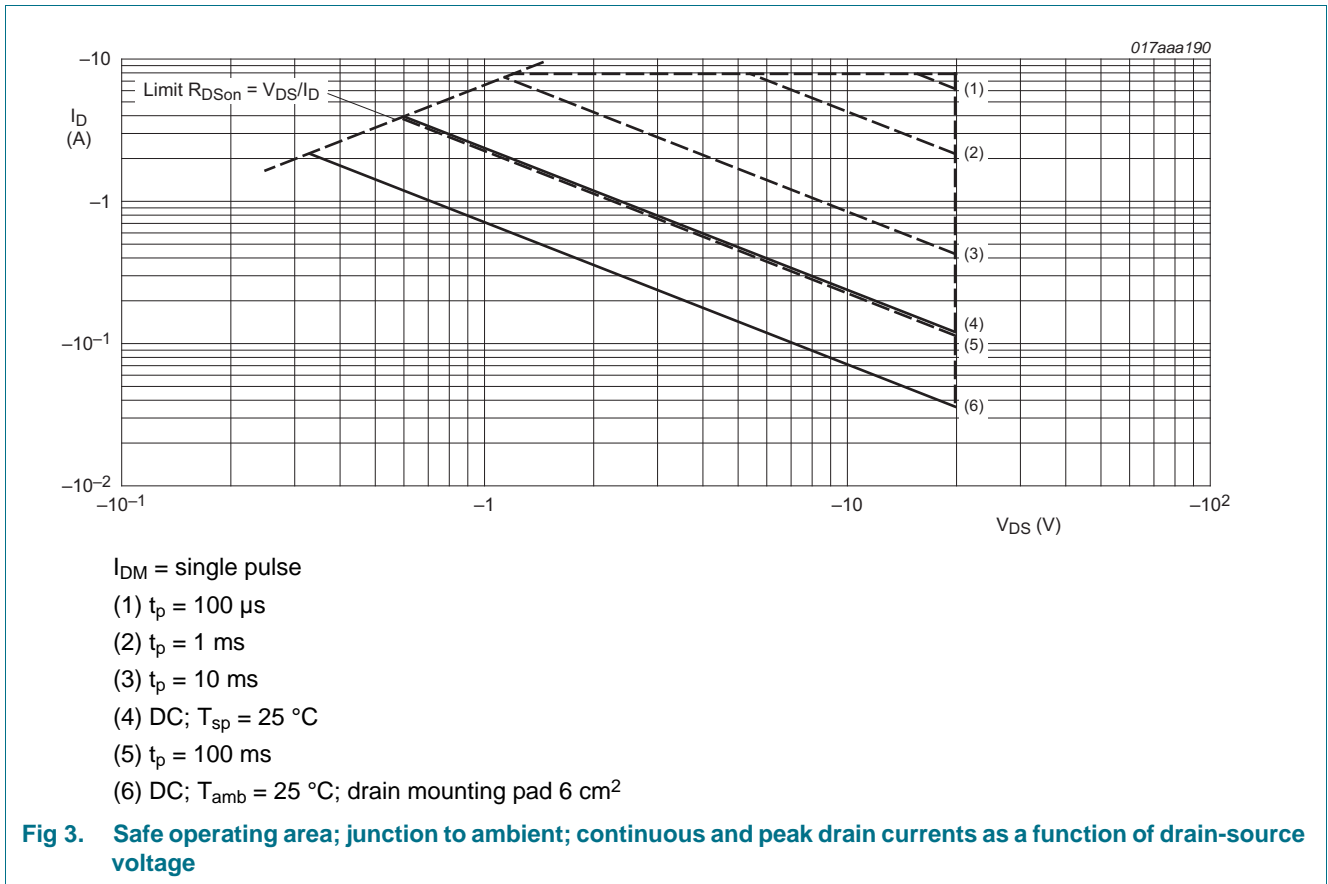
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> = 25 °C	-	-20	V	
V <sub>GS</sub>	gate-source voltage		-12	12	V	
I <sub>D</sub>	drain current	V <sub>GS</sub> = -4.5 V; T <sub>j</sub> = 25 °C	[1]	-	-2	A
		V <sub>GS</sub> = -4.5 V; T <sub>j</sub> = 100 °C	[1]	-	-1.3	A
I <sub>DM</sub>	peak drain current	T <sub>amb</sub> = 25 °C; single pulse; t <sub>p</sub> ≤ 10 μs	-	-8	A	
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C	[2]	-	375	mW
			[1]	-	725	mW
		T <sub>sp</sub> = 25 °C		-	2400	mW
T <sub>j</sub>	junction temperature		-55	150	°C	
T <sub>amb</sub>	ambient temperature		-55	150	°C	
T <sub>stg</sub>	storage temperature		-65	150	°C	
<b>Source-drain diode</b>						
I <sub>S</sub>	source current	T <sub>amb</sub> = 25 °C	[1]	-	-0.7	A

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.





## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	290	334	K/W
			[2]	-	150	173	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	45	52	K/W	

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain  $6 \text{ cm}^2$ .

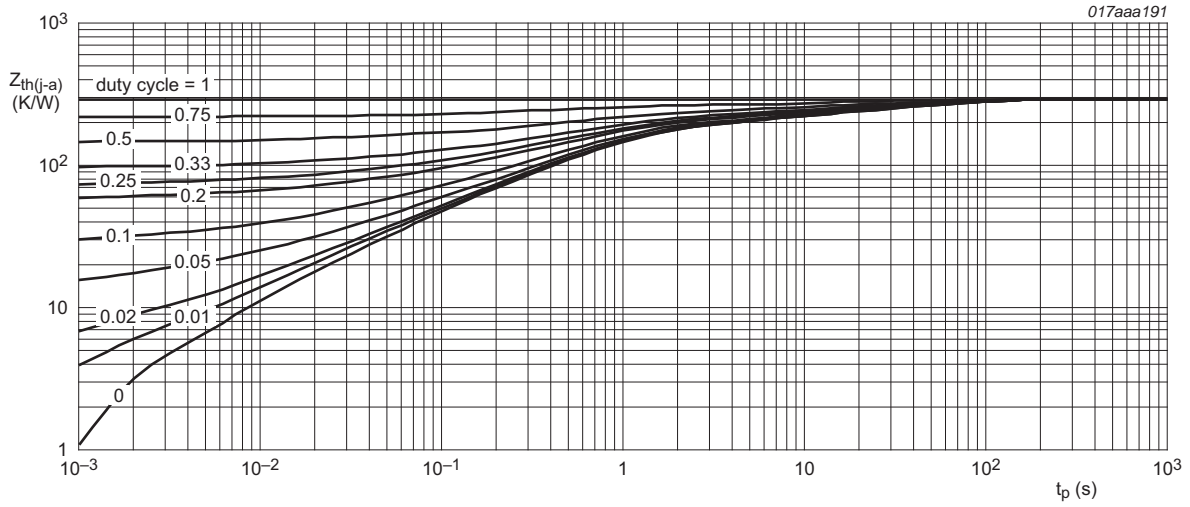


Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

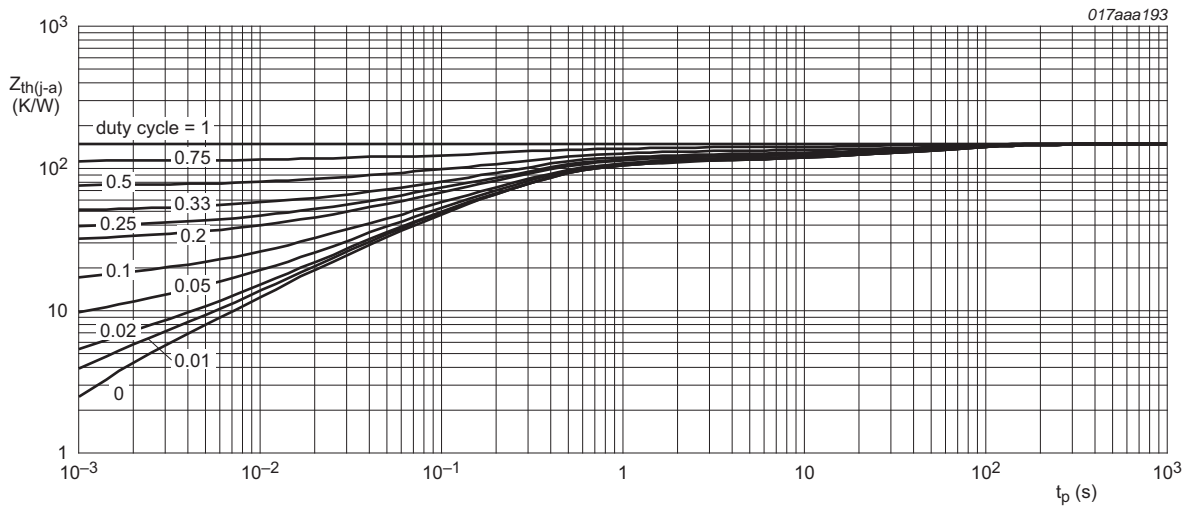
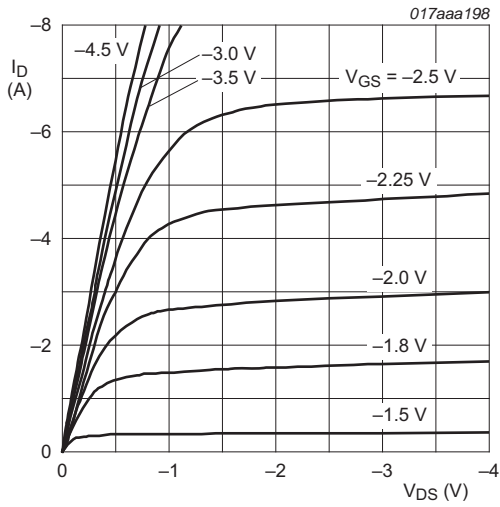


Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 7. Characteristics

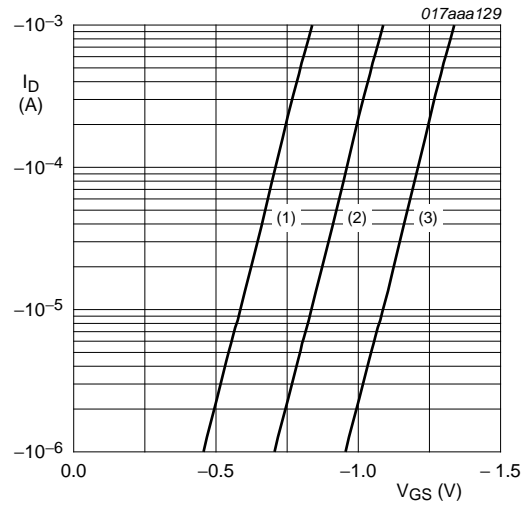
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = -250 \mu A$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ\text{C}$	-20	-	-	V
$V_{GSth}$	gate-source threshold voltage	$I_D = -250 \mu A$ ; $V_{DS} = V_{GS}$ ; $T_j = 25 \text{ }^\circ\text{C}$	-0.65	-0.9	-1.15	V
$I_{DSS}$	drain leakage current	$V_{DS} = -20 V$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	-	-1	$\mu A$
		$V_{DS} = -20 V$ ; $V_{GS} = 0 V$ ; $T_j = 150 \text{ }^\circ\text{C}$	-	-	-15	$\mu A$
$I_{GSS}$	gate leakage current	$V_{GS} = 12 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	-	100	nA
		$V_{GS} = -12 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	-	-100	nA
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = -4.5 V$ ; $I_D = -2 A$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	90	115	m $\Omega$
		$V_{GS} = -4.5 V$ ; $I_D = -2 A$ ; $T_j = 150 \text{ }^\circ\text{C}$	-	130	166	m $\Omega$
		$V_{GS} = -2.5 V$ ; $I_D = -2 A$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	125	160	m $\Omega$
$g_{fs}$	forward transconductance	$V_{DS} = -5 V$ ; $I_D = -2 A$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	6.3	-	S
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$V_{DS} = -10 V$ ; $I_D = -1 A$ ; $V_{GS} = -4.5 V$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	4.8	7.2	nC
$Q_{GS}$	gate-source charge		-	1.1	-	nC
$Q_{GD}$	gate-drain charge		-	1	-	nC
$C_{iss}$	input capacitance	$V_{DS} = -10 V$ ; $f = 1 \text{ MHz}$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	560	-	pF
$C_{oss}$	output capacitance		-	80	-	pF
$C_{rss}$	reverse transfer capacitance		-	55	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = -10 V$ ; $V_{GS} = -4.5 V$ ; $R_{G(ext)} = 6 \Omega$ ; $T_j = 25 \text{ }^\circ\text{C}$ ; $I_D = -2.5 A$	-	13	-	ns
$t_r$	rise time		-	35	-	ns
$t_{d(off)}$	turn-off delay time		-	39	-	ns
$t_f$	fall time		-	25	-	ns
<b>Source-drain diode</b>						
$V_{SD}$	source-drain voltage	$I_S = -0.7 A$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ\text{C}$	-	-0.7	-1.2	V



$T_j = 25\text{ }^\circ\text{C}$

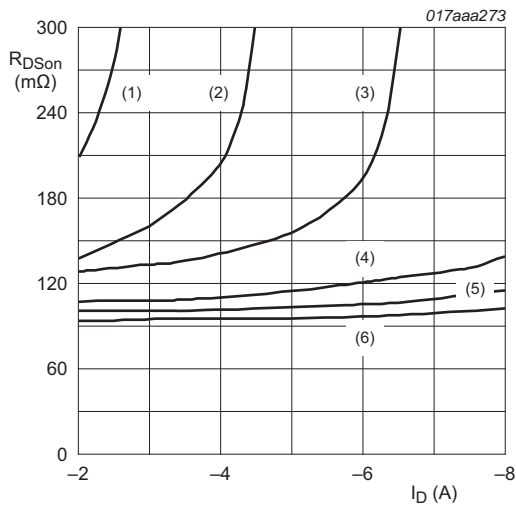
**Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values**



$T_j = 25\text{ }^\circ\text{C}; V_{DS} = -3\text{ V}$

- (1) minimum values
- (2) typical values
- (3) maximum values

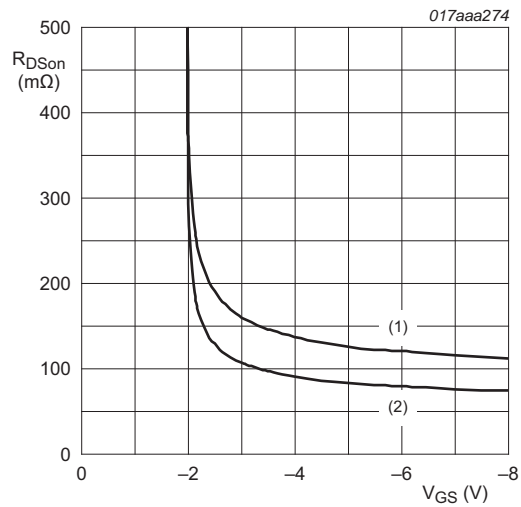
**Fig 7. Sub-threshold drain current as a function of gate-source voltage**



$T_j = 25\text{ }^\circ\text{C}$

- (1)  $V_{GS} = -2.0\text{ V}$
- (2)  $V_{GS} = -2.25\text{ V}$
- (3)  $V_{GS} = -2.5\text{ V}$
- (4)  $V_{GS} = -3.0\text{ V}$
- (5)  $V_{GS} = -3.5\text{ V}$
- (6)  $V_{GS} = -4.5\text{ V}$

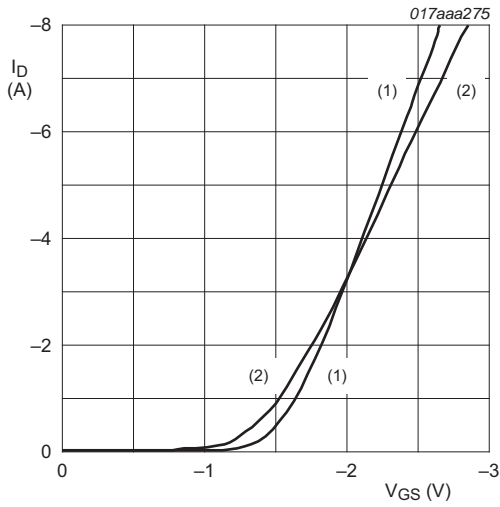
**Fig 8. Drain-source on-state resistance as a function of drain current; typical values**



$I_D = -2.5\text{ A}$

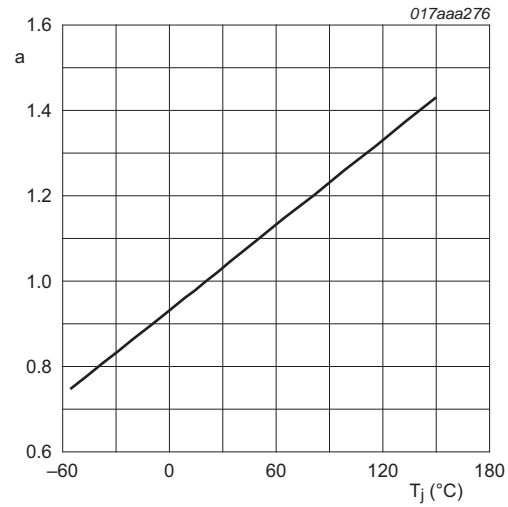
- (1)  $T_j = 125\text{ }^\circ\text{C}$
- (2)  $T_j = 25\text{ }^\circ\text{C}$

**Fig 9. Drain-source on-state resistance as a function of gate-source voltage; typical values**



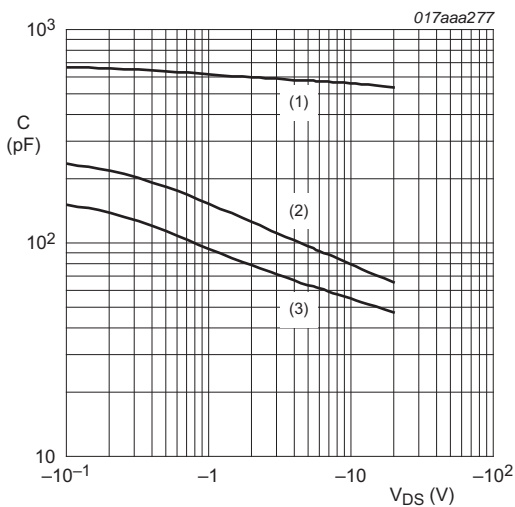
$V_{DS} > I_D \times R_{DS(on)}$   
 (1)  $T_j = 25\text{ °C}$   
 (2)  $T_j = 150\text{ °C}$

**Fig 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values**



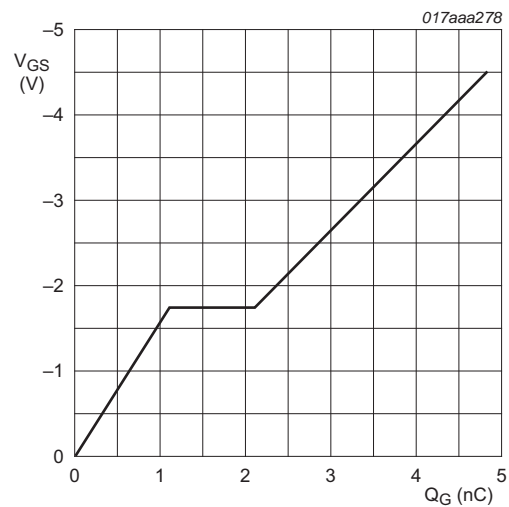
$$a = \frac{R_{DS(on)}}{R_{DS(on)(25\text{°C})}}$$

**Fig 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values**



$f = 1\text{ MHz}; V_{GS} = 0\text{ V}$   
 (1)  $C_{iss}$   
 (2)  $C_{oss}$   
 (3)  $C_{rss}$

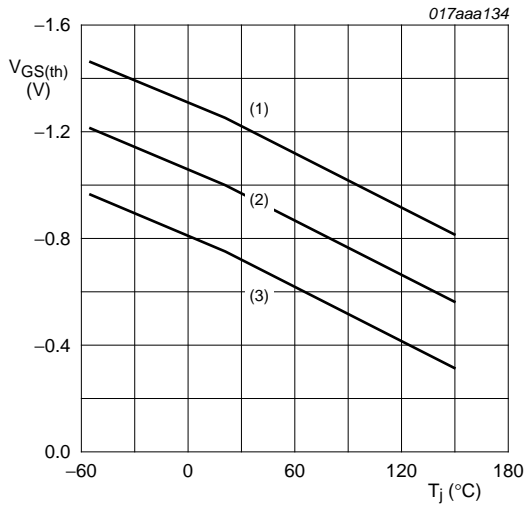
**Fig 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values**



$I_D = -3\text{ A}; V_{DS} = -10\text{ V}; T_{amb} = 25\text{ °C}$

**Fig 13. Gate-source voltage as a function of gate charge; typical values**





$I_D = -0.25 \text{ mA}; V_{DS} = V_{GS}$

- (1) maximum values
- (2) typical values
- (3) minimum values

Fig 14. Gate-source threshold voltage as a function of junction temperature

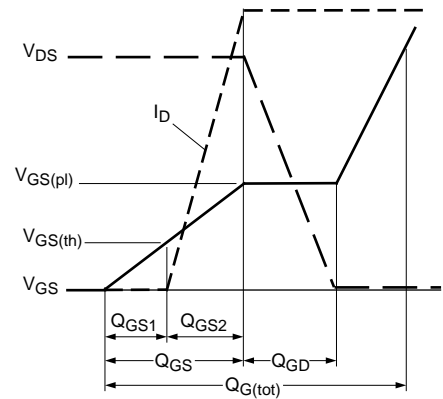
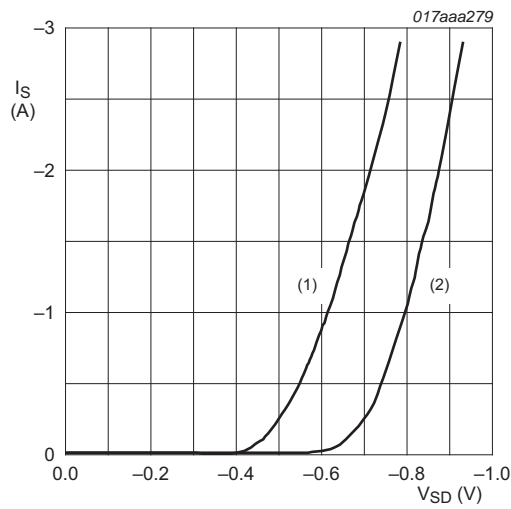


Fig 15. Gate charge waveform definitions



$V_{GS} = 0 \text{ V}$

- (1)  $T_j = 150 \text{ }^\circ\text{C}$
- (2)  $T_j = 25 \text{ }^\circ\text{C}$

Fig 16. Source current as a function of source-drain voltage; typical values

8. Test information

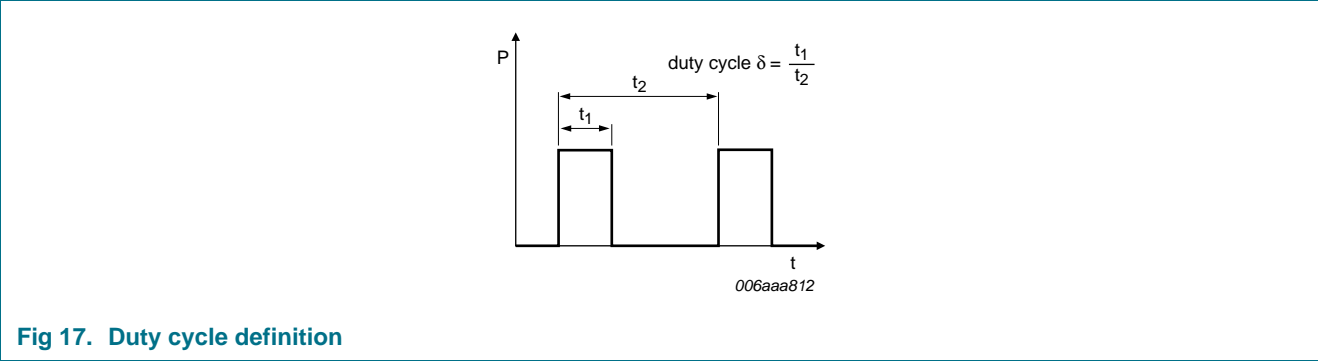


Fig 17. Duty cycle definition

9. Package outline

Plastic surface-mounted package; 6 leads

SOT363

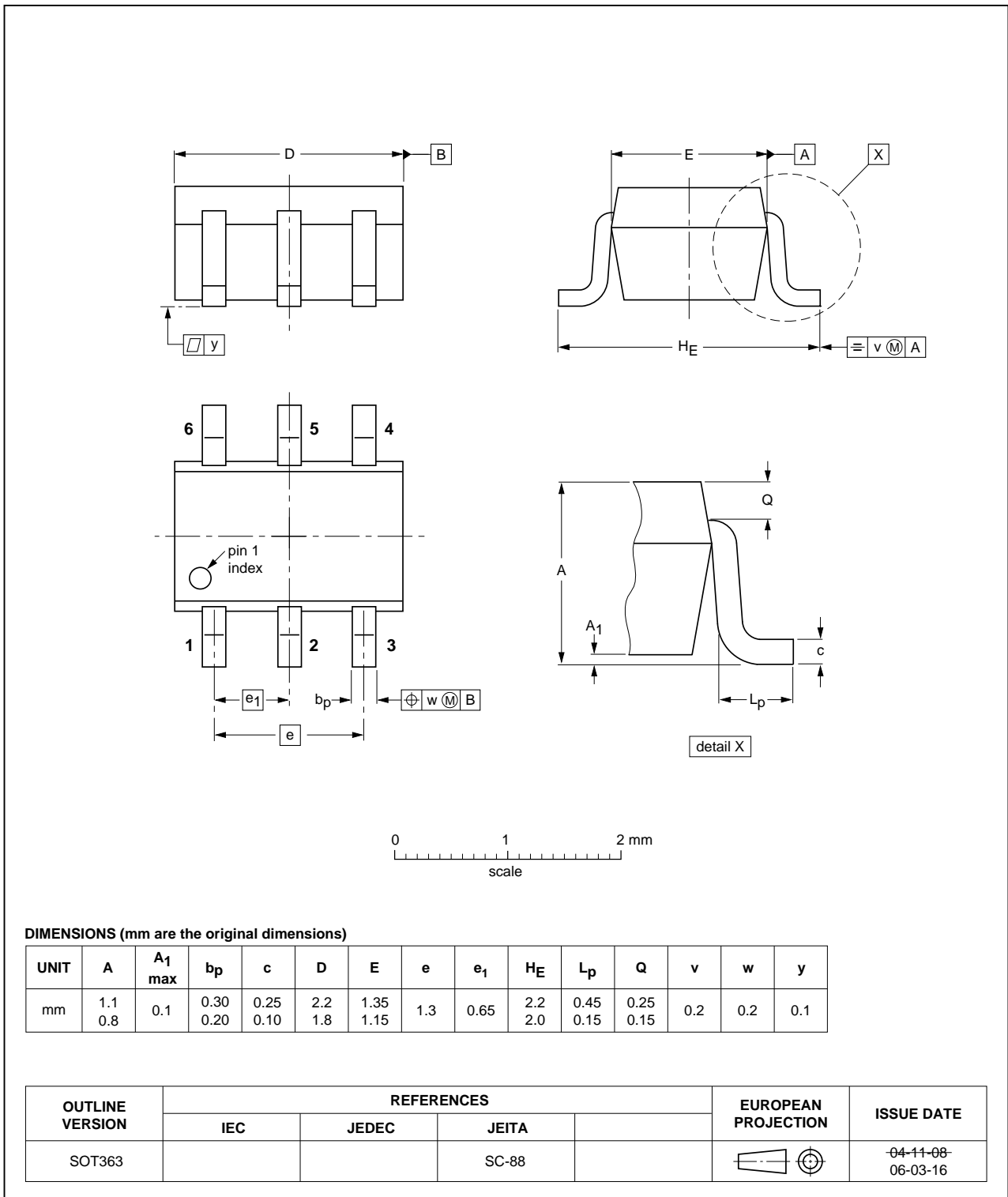


Fig 18. Package outline SOT363 (TSSOP6)

### 10. Soldering

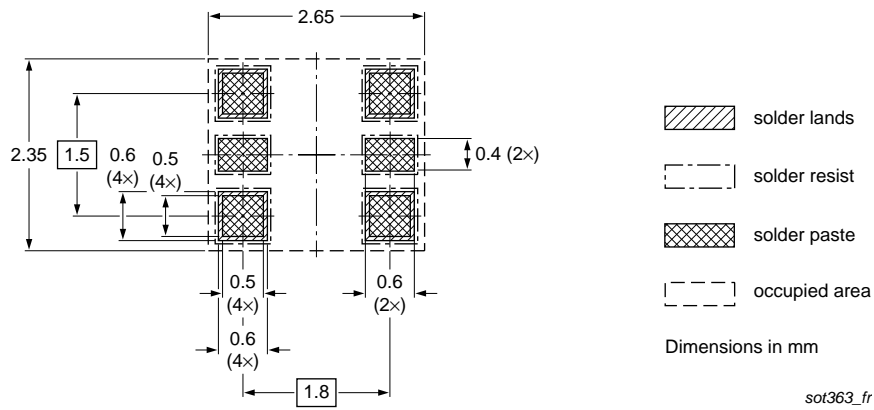


Fig 19. Reflow soldering footprint for SOT363 (TSSOP6)

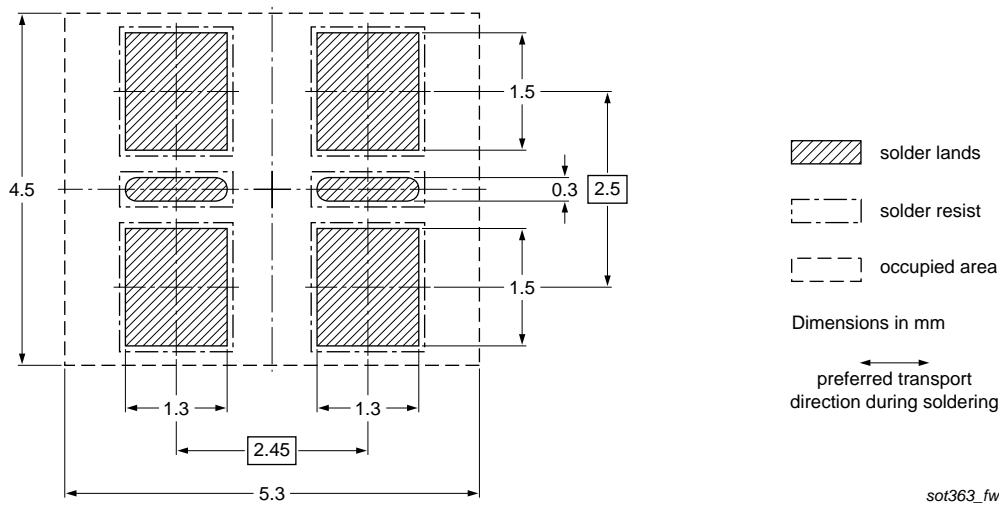


Fig 20. Wave soldering footprint for SOT363 (TSSOP6)

## 11. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMG85XP v.N	20110628	Product data sheet	-	-

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1]</sup> <sup>[2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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## 14. Contents

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<b>1</b>	<b>Product profile</b> . . . . .	<b>1</b>
1.1	General description . . . . .	1
1.2	Features and benefits . . . . .	1
1.3	Applications . . . . .	1
1.4	Quick reference data . . . . .	1
<b>2</b>	<b>Pinning information</b> . . . . .	<b>2</b>
<b>3</b>	<b>Ordering information</b> . . . . .	<b>2</b>
<b>4</b>	<b>Marking</b> . . . . .	<b>2</b>
<b>5</b>	<b>Limiting values</b> . . . . .	<b>3</b>
<b>6</b>	<b>Thermal characteristics</b> . . . . .	<b>4</b>
<b>7</b>	<b>Characteristics</b> . . . . .	<b>6</b>
<b>9</b>	<b>Package outline</b> . . . . .	<b>11</b>
<b>10</b>	<b>Soldering</b> . . . . .	<b>12</b>
<b>11</b>	<b>Revision history</b> . . . . .	<b>13</b>
<b>12</b>	<b>Legal information</b> . . . . .	<b>14</b>
12.1	Data sheet status . . . . .	14
12.2	Definitions . . . . .	14
12.3	Disclaimers . . . . .	14
12.4	Trademarks . . . . .	15
<b>13</b>	<b>Contact information</b> . . . . .	<b>15</b>

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